

PATENT ASSIGNMENT COVER SHEET

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| SUBMISSION TYPE: | NEW ASSIGNMENT |
| NATURE OF CONVEYANCE: | ASSIGNMENT |
| CONVEYING PARTY DATA | |
| Name | Execution Date |
| CHIH-HAO CHANG | 09/12/2016 |
| HSIN-HUNG LIAO | 09/12/2016 |
| HAO-YI TSAI | 09/12/2016 |
| CHIEN-LING HWANG | 09/12/2016 |
| WEI-SEN CHANG | 09/08/2016 |
| TSUNG-HSIEN CHIANG | 09/12/2016 |
| TIN-HAO KUO | 09/12/2016 |
| RECEIVING PARTY DATA | |
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| State/Country: | TAIWAN |
| Postal Code: | 30078 |
| PROPERTY NUMBERS Total: 1 | |
| Property Type | Number |
| Application Number: | 15270008 |
| CORRESPONDENCE DATA | |
| Fax Number: | |
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| ATTORNEY DOCKET NUMBER: | 63181-US-PA |
| NAME OF SUBMITTER: | BELINDA LEE |
| SIGNATURE: | /Belinda Lee/ |
| DATE SIGNED: | 09/20/2016 |

PATENT

Total Attachments: 4

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

☒ Declaration Submitted With Initial Filing

OR

☐ Declaration Submitted After Initial Filing (surcharge 37 CFR 1.16(f) required)

(Title of the Invention)

**INTEGRATED FAN-OUT PACKAGE AND METHOD OF FABRICATING
THE SAME**

As a below named inventor (hereinafter designated as the undersigned), I hereby declare that:

This declaration is directed to:

☒ The attached application,

OR

☐ United States Application Number or PCT International application number _____

Filed on _____.

The above-identified application was made or authorized to be made by me.

I believe I am the original inventor or an original joint inventor of a claimed invention in the application.

The undersigned hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

WHEREAS, the undersigned has invented certain new and useful improvements described in the application identified.

WHEREAS 1. Taiwan Semiconductor Manufacturing Co., Ltd.
of No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78,
R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring the undersigned's interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by the undersigned, the undersigned has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said rights, title and interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said the undersigned had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

The undersigned further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION

Signature: Chih-Hao Chang Date: 2016. 9/12th

Legal Name of Sole or First Inventor: Chih-Hao Chang

Residence: Hsinchu County, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Hsin-Hung Liao Date: 9/12/2016

Legal Name of Additional Joint Inventor, if any: Hsin-Hung Liao

Residence: Taipei City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Hao-Yi Tsai Date: 2016. 9. 12

Legal Name of Additional Joint Inventor, if any: Hao-Yi Tsai

Residence: Hsinchu City, Taiwan

Mailing Address: c/o No.8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu, Taiwan 300-78, R.O.C.

Signature: Chien-Ling Hwang Date: 2016. 9. 12

Legal Name of Additional Joint Inventor, if any: Chien-Ling Hwang

Residence: Hsinchu City, Taiwan

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Signature: Wei-Sen Chang Date: 2016. 9. 8

Legal Name of Additional Joint Inventor, if any: Wei-Sen Chang

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Signature: Tsung-Hsien Chiang Date: 2016. 9. 12

Legal Name of Additional Joint Inventor, if any: Tsung-Hsien Chiang

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**DECLARATION AND ASSIGNMENT
FOR UTILITY OR DESIGN PATENT APPLICATION**

Signature: Tin Hao Kuo Date: 9/12/2016
Legal Name of Additional Joint Inventor, if any: Tin-Hao Kuo
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